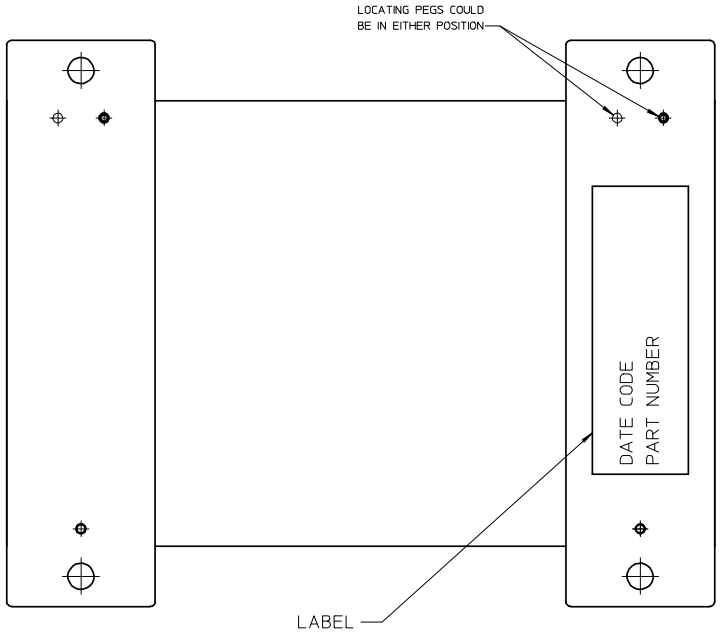

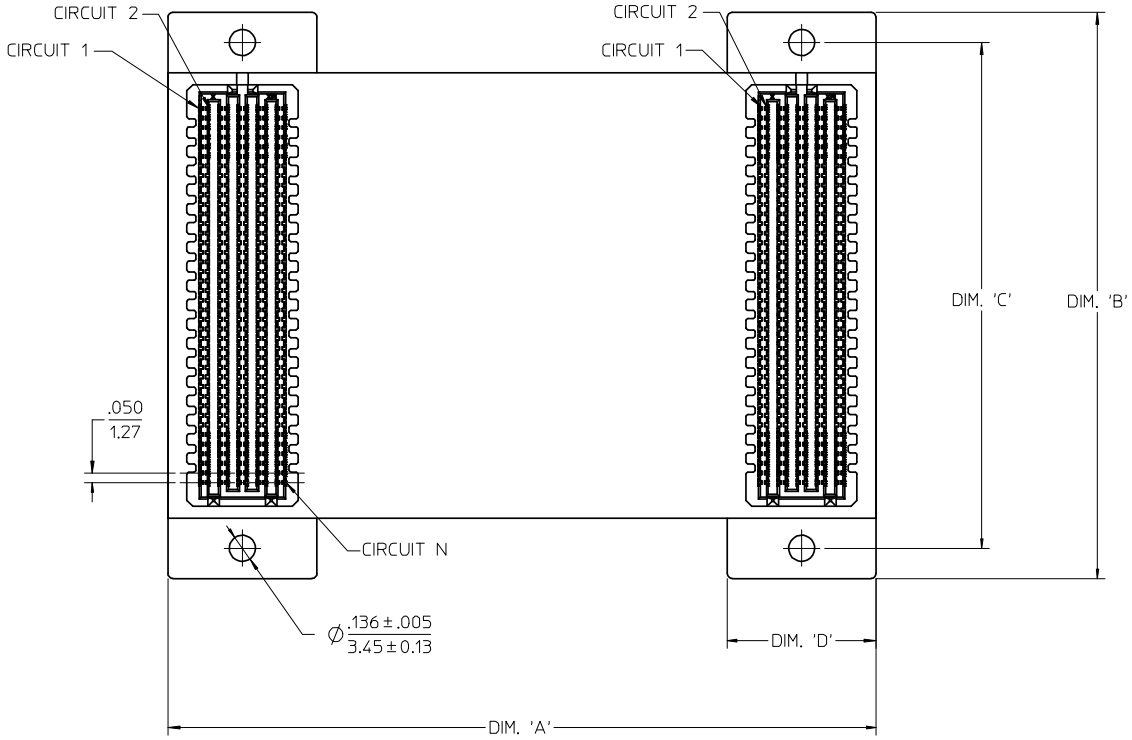

NOTES:

1. MATERIALS:
   TERMINALS: COPPER ALLOY
   HOUSING: HIGH TEMP THERMOPLASTIC, COLOR: BLACK, 94V-0
   FLEX CIRCUIT - POLYIMIDE
   HARDBOARD - FR4

2. PLATING: SELECTIVE GOLD IN CONTACT AREA OVER NICKEL, TIN ON TAIL OVER NICKEL.

3. PACKAGING: PARTS TO BE PACKAGED PER PK-110299-001.

4. FOR POINT-TO-PONT PINOUT ON ALL CIRCUIT SIZES SEE SHEET 2.

5. CONFORMS TO IPC-6011 "GENERIC PERFORMANCE SPECIFICATION FOR PRINTED BOARDS".
   IPC-6013A "QUALIFICATION AND PERFORMANCE SPECIFICATION FOR FLEXIBLE PRINTED BOARDS".
   IPC-A-610, CLASS 2 "ACCEPTABILITY OF ELECTRONIC ASSEMBLIES".
   IPC-A-600, CLASS 2 ACCEPTABILITY OF PRINTED BOARDS".

6. ELECTRICAL TESTING: 100% CONTINUITY CHECK.

7. ASSEMBLY IS RoHS COMPLIANT.

INITIAL RELEASE	2008/05/02		
EC NO: CFP2008-0004			
DRWN:DSCHMIDG	2008/03/11		
CH'KD:			
APPR:			
A	REV	DESCRIPTION	

QUALITY SYMBOLS: ▼=0, (C)=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .010
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM/IN	SCALE: 2:1	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION
DRAWN BY: DSCHMIDGALL	DATE: 10/25/2006	TITLE: SEARAY (PLUG) FLEX CIRCUIT ASSEMBLY	
CHECKED BY: DSCHMIDGALL	DATE: 10/25/2006		
APPROVED BY	DATE	molex MOLEX INCORPORATED	
MATERIAL NO.: SEE CHART		DOCUMENT NO.: SD-110299-001	SHEET NO.: 1 OF 4
SIZE: C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

CIRCUIT SIZE	FLEX ASSEMBLY MATERIAL NUMBER	HOUSING HEIGHT	DIM. A	DIM. B	DIM. C	DIM. D	NUMBER OF POSITIONS PER ROW	NUMBER OF ROWS
400	110299-0001	.280/7.11	3.690/93.73	2.950/74.93	2.635/66.93	.775/19.69	40	10

PIN OUT

(FOR ALL CIRCUIT SIZES)

CONNECTOR #1	CONNECTOR #2
A1	B1
A2	B2
A3	B3
A4	B4
A5	B5
A6	B6
A.	B.
A..	B..

SEE SHEET 1
EC NO: CFP2008-0004
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MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-110299-001
SHEET NO.: 2 OF 4
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CIRCUIT SIZE	FLEX ASSEMBLY MATERIAL NUMBER	HOUSING HEIGHT	DIM. A	DIM. B	DIM. C	DIM. D	NUMBER OF POSITIONS PER ROW	NUMBER OF ROWS
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SEE SHEET 2 FOR PIN OUT

SEE SHEET 1
EC NO: CFP2008-0004
DRWN:DSCHMIDG 2008/03/11
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SHEET NO.: 3 OF 4
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CIRCUIT SIZE	FLEX ASSEMBLY MATERIAL NUMBER	HOUSING HEIGHT	DIM. A	DIM. B	DIM. C	DIM. D	NUMBER OF POSITIONS PER ROW	NUMBER OF ROWS
160	110299-0004 110299-0005	.199/5.05 .258/6.55	15.375/390.53	2.295/58.30	1.980/50.29	.620/15.75	20	8

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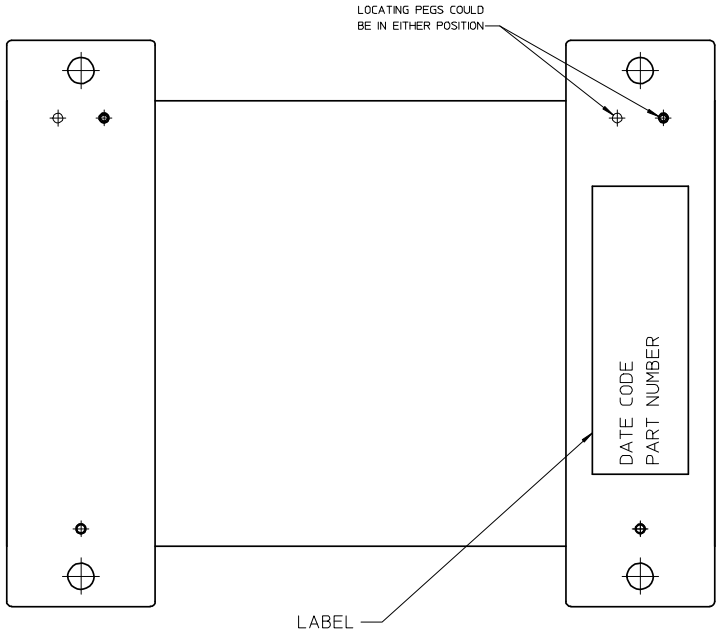

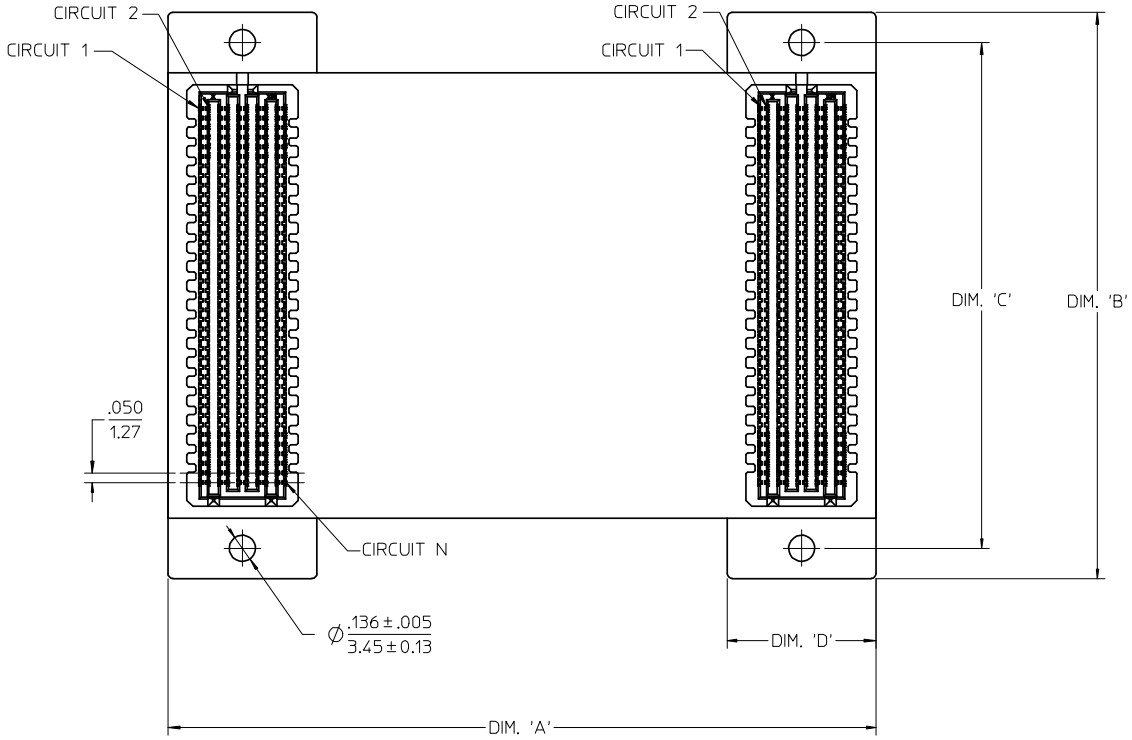

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MATERIAL NO.: SEE CHART		DOCUMENT NO.: SD-110299-001	SHEET NO.: 1 OF 4
SIZE: C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

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